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IN THE CLAIMS

Please cancel claims 1-6.

7. (Original) A method for forming an electronic package comprising the steps of:

attaching an electronic chip to a support substrate, wherein the electronic chip includes a bond pad on an outer surface;

attaching a conductive stud to the bond pad;

encapsulating the electronic chip to form a sub-assembly having an upper surface;

forming an opening in the upper surface to expose the conductive stud;

forming a barrier layer on the conductive stud; and

attaching a solder bump to the barrier layer.

8. (Original) The method of claim 7 wherein the step of forming the barrier layer includes forming a nickel barrier layer.

9. (Original) The method of claim 7 wherein the step of forming the barrier layer comprises the steps of:

placing the sub-assembly in an electroless plating bath; and

injecting plating solution towards the opening to form the barrier layer on the conductive stud.

10. (Original) The method of claim 9 further comprising the step of agitating the electroless plating bath.

11. (Original) The method of claim 9 wherein the step of placing the sub-assembly includes placing the sub-assembly in an electroless nickel plating solution.

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12. (Original) The method of claim 9 further comprising the step of masking the support substrate.

13. (Original) The method of claim 7 wherein the step of attaching the conductive stud includes attaching a gold stud.

14. (Original) A method for forming a direct chip attach device comprising the steps of:

providing a sub-assembly comprising a lead frame, a chip attached the lead frame, a bond pad formed on an outer surface of the chip, a conductive bump attached to the bond pad, and an encapsulating layer covering the chip, wherein the encapsulating layer has an opening to expose the conductive bump;

placing the sub-assembly in an electroless plating solution; and

injecting electroless plating solution towards the opening to form a barrier layer on the conductive bump.

15. (Original) The method of claim 14 further comprising the step of covering exposed portions of the lead frame with a masking layer.

16. (Original) The method of claim 14 wherein the step of placing the sub-assembly includes placing the sub-assembly in an electroless nickel plating bath.

17. (Original) The method of claim 14 further comprising the step of coupling a solder bump to the barrier layer.

18. (Original) The method of claim 14 further comprising the step of agitating the electroless plating solution.

Please cancel claims 19-20.

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Please add the following new claims:

21. (New) A process for forming a direct chip attach device comprising the steps of:
- providing the direct chip attach device including an encapsulated electronic chip having an opening to expose a first conductive portion coupled to the electronic chip;
  - forming a barrier layer on the first conductive portion; and
  - attaching a second conductive portion to the barrier layer.
22. (New) The process of claim 21 wherein the step of providing the direct chip attach device includes providing an encapsulated power MOSFET device.
23. (New) The process of claim 21 wherein the step of providing the direct chip attach device includes providing the encapsulated electronic chip, wherein the encapsulated electronic chip is attached to a lead frame including an exposed flag, the process further including the steps of:
- forming the barrier layer on the exposed flag; and
  - attaching a third conductive portion to the barrier layer on the exposed flag.
24. (New) The process of claim 21 wherein the step of forming the barrier layer includes forming a barrier layer including nickel.
25. (New) The process of claim 21 wherein the step of forming the barrier layer comprises the steps of:
- placing the sub-assembly in an electroless plating bath; and
  - injecting plating solution towards the opening to form the barrier layer on the conductive stud.

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26. (New) The process of claim 25 further comprising the step of agitating the electroless plating bath.

27. (New) The process of claim 25 wherein the step of placing the sub-assembly includes placing the sub-assembly in an electroless nickel plating solution.

28. (New) The process of claim 21 wherein the step of providing the direct chip attach device includes providing direct chip attach device wherein the first conductive portion comprises gold.